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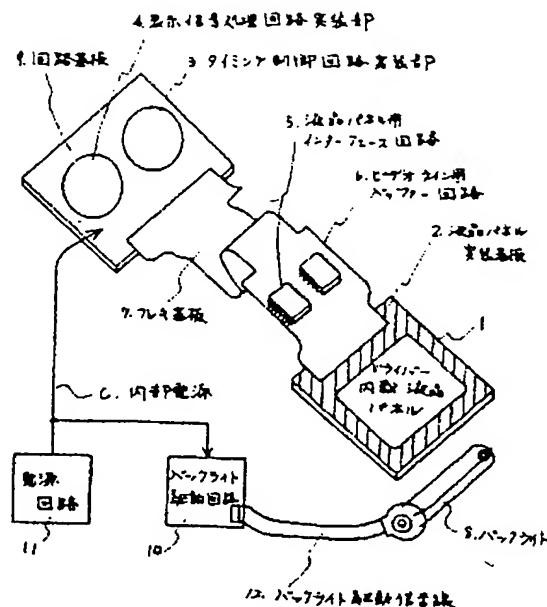
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TITLE : PACKAGING STRUCTURE FOR LIQUID CRYSTAL DISPLAY DEVICE



ABSTRACT : PURPOSE: To reduce electric power consumption and to miniaturize a circuit board by packaging at least either of an interface circuit and video line buffer circuit to a flexible substrate which transmits signals to a packaging substrate.

CONSTITUTION: A driver-contg. liquid crystal panel 1 is packaged to the liquid crystal panel packaging substrate 2. A timing control circuit 3 and a display signal forming circuit 4 are packaged on the circuit board 9. The output signals from the circuit board 9 are sent to the flexible substrate 7. The interface circuit 5 and the buffer circuit 6 for video lines are packaged on the substrate 7. The signals processed by the circuits 5 and 6 are sent to the panel 1. Displaying is executed by these signals. The load capacity of the panel 1 viewed from the output stage of the circuits 5 and 6 is thereby decreased as the capacity of the substrate 7 is negligible. Since the number of the circuits to be packaged on the circuit board 9 is decreased, the circuit board 9 is reduced in size.

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